

High Temperature Silicon Carbide Power Schottky Diode

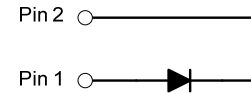
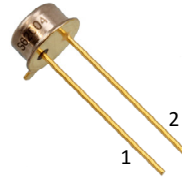
V_{RRM}	=	100 V
$I_F (T_C=25^\circ\text{C})$	=	4 A
Q_C	=	9 nC

Features

- 100 V Schottky rectifier
- 210 °C maximum operating temperature
- Zero reverse recovery charge
- Superior surge current capability
- Positive temperature coefficient of V_F
- Temperature independent switching behavior
- Lowest figure of merit Q_C/I_F
- Available screened to Mil-PRF-19500

Package

- RoHS Compliant



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Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

Applications

- Down Hole Oil Drilling
- Geothermal Instrumentation
- Solenoid Actuators
- General Purpose High-Temperature Switching
- Amplifiers
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)

Maximum Ratings at $T_j = 210^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Repetitive peak reverse voltage	V_{RRM}			100		V
Continuous forward current	I_F	$T_C = 25^\circ\text{C}$		4		A
Continuous forward current	I_F	$T_C \leq 180^\circ\text{C}$		2		A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 180^\circ\text{C}$		4		A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$		10		A
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\ \mu\text{s}$		65		A
I^2t value	$\int i^2 dt$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$		0.5		A ² S
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$		64		W
Operating and storage temperature	T_j, T_{stg}			-55 to 210		°C

Electrical Characteristics at $T_j = 210^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 1\text{ A}, T_j = 25^\circ\text{C}$		1.6		V
		$I_F = 1\text{ A}, T_j = 210^\circ\text{C}$		2.6		
Reverse current	I_R	$V_R = 100\text{ V}, T_j = 25^\circ\text{C}$		1	5	μA
		$V_R = 100\text{ V}, T_j = 210^\circ\text{C}$		5	50	
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 210^\circ\text{C}$		9		nC
Switching time	t_s	$V_R = 100\text{ V}$ $V_R = 100\text{ V}$		< 17		ns
Total capacitance	C	$V_R = 1\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		76		pF
		$V_R = 100\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		20		

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	5.55	°C/W
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Mechanical Properties

Mounting torque	M	0.6	Nm
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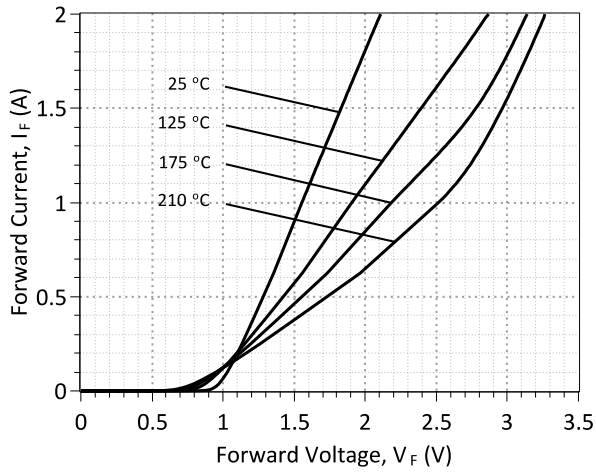


Figure 1: Typical Forward Characteristics

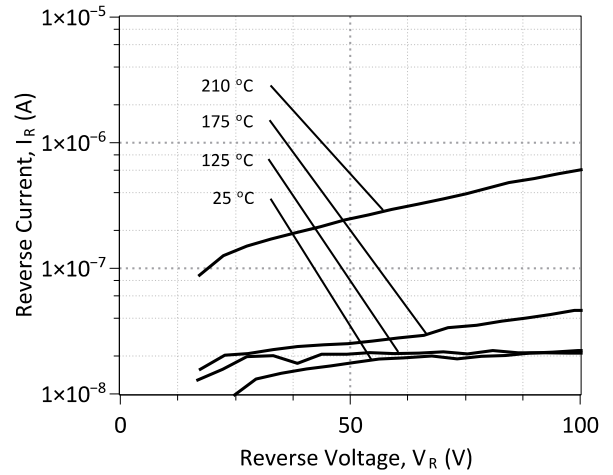


Figure 2: Typical Reverse Characteristics

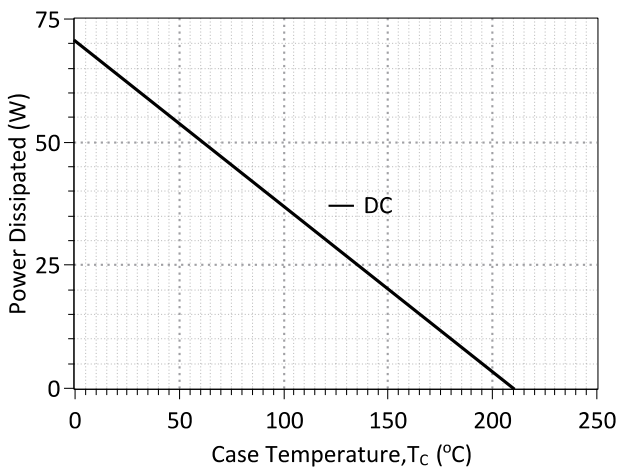
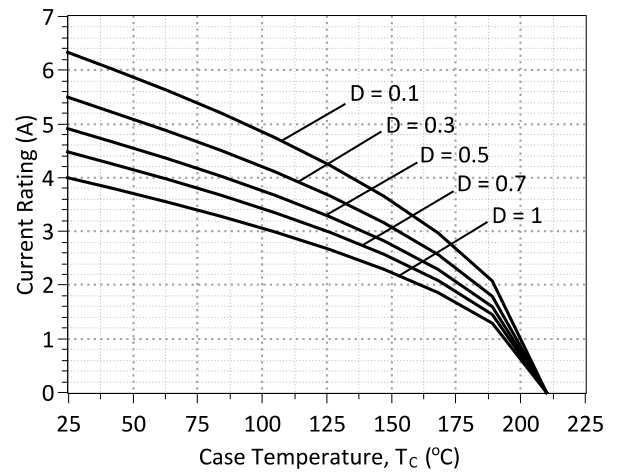


Figure 3: Power Derating Curve



**Figure 4: Current Derating Curves ($D = t_p/T$, $t_p = 400 \mu s$)
(Considering worst case Z_{th} conditions)**

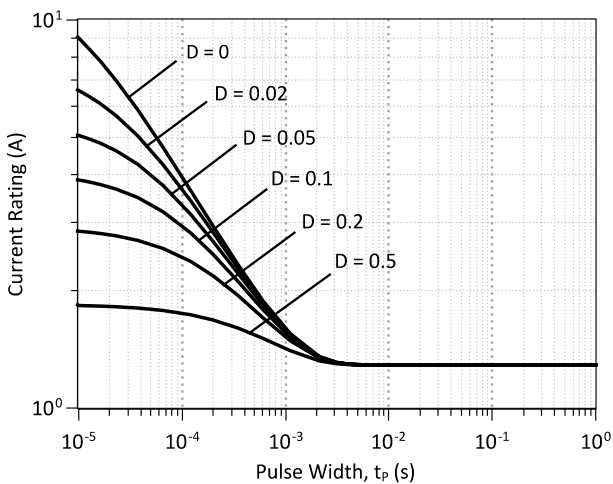


Figure 5: Current vs Pulse Duration Curves at $T_C = 190 \text{ }^\circ\text{C}$

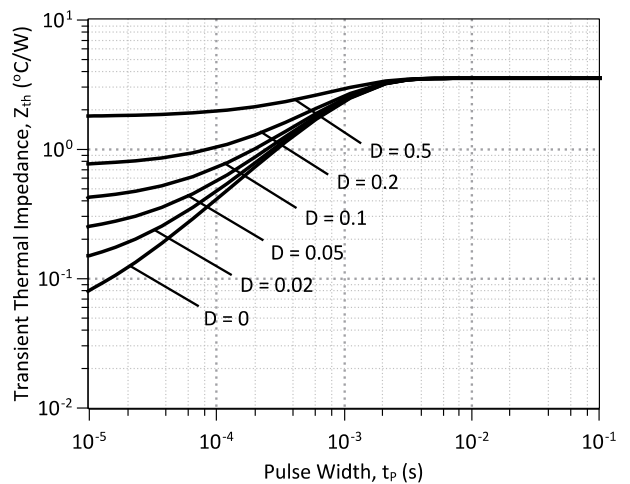
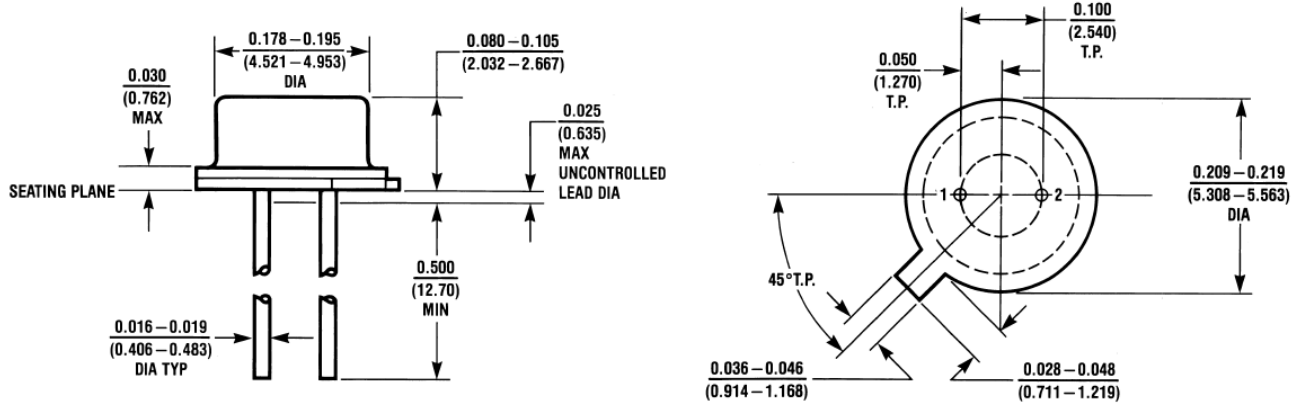


Figure 6: Transient Thermal Impedance

Package Dimensions:
TO-46
PACKAGE OUTLINE

NOTE

1. CONTROLLED DIMENSION IS INCH.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History

Date	Revision	Comments	Supersedes
2014/08/29	0	Initial release	

Published by
 GeneSiC Semiconductor, Inc.
 43670 Trade Center Place Suite 155
 Dulles, VA 20166

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SPICE Model Parameters

This is a secure document. Copy this code from the SPICE model PDF file on our website into a SPICE software program for simulation of the GB02SHT01-46.

```
*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      29-AUG-2014   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*
*      COPYRIGHT (C) 2014 GeneSiC Semiconductor Inc.
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*
*      These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
*      OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
*      TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
*      PARTICULAR PURPOSE."
*      Models accurate up to 2 times rated drain current.
*
*      Start of GB02SHT01-46 SPICE Model
*
.SUBCKT GB02SHT01ANODE KATHODE
D1 ANODE KATHODE GB02SHT01_25C; Call the Schottky Diode Model
D2 ANODE KATHODE GB02SHT01_PIN; Call the PiN Diode Model
.MODEL GB02SHT01_25C D
+ IS      3.57E-18          RS      0.49751
+ TRS1    0.0057           TRS2    2.40E-05
+ N       1                IKF     322
+ EG      1.2              XTI     3
+ CJO     9.12E-11         VJ      0.371817384
+ M       1.527759838     FC       0.5
+ TT      1.00E-10        BV       100
+ IBV     1.00E-03        VPK     100
+ IAVE    2                TYPE    SiC_Schottky
+ MFG     GeneSiC_Semiconductor
.MODEL GB02SHT01_PIN D
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+ N       5                IKF     800
+ EG      3.23             XTI     -14
+ FC      0.5              TT       0
+ BV      100              IBV     1.00E-03
+ VPK     100              IAVE    2
+ TYPE    SiC_PiN
.ENDS
*
*      End of GB02SHT01 SPICE Model
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